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(71) Applicant: **FUJIFILM ELECTRONIC MATERIALS U.S.A., INC.** [US/US]; 80 Circuit Drive, N. Kingstown, Rhode Island 02852 (US).

(72) Inventors: **MALIK, Sanjay**; 40 Gaywood Avenue, Attleboro, Massachusetts 02703 (US). **DE, Binod B.**; 3 Stanley Street, Attleboro, Massachusetts 02703 (US). **REINERTH, William A.**; 85 Heath Street, Riverside, Rhode Island 02915 (US). **DIMOV, Ognian**; 211 Blade Street, Warwick, Rhode Island 02886 (US). **DILLOCKER, Stephanie**; 26 Nathaniel Point Road, Attleboro, Massachusetts 02703 (US).

(74) Agent: **ZHANG, Tony**; Fish & Richardson P.C., P.O. Box 1022, New York, New York 55440-1022 (US).

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(54) Title: DIELECTRIC FILM FORMING COMPOSITIONS

(57) Abstract: This disclosure relates to a dielectric film forming composition that includes a plurality of (meth)acrylate containing compounds, at least one fully imidized polyimide polymer, and at least one solvent.

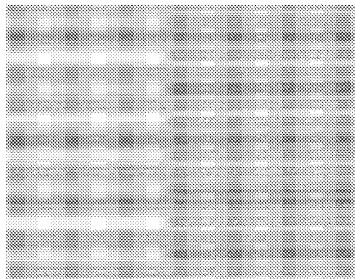


Figure 1A



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